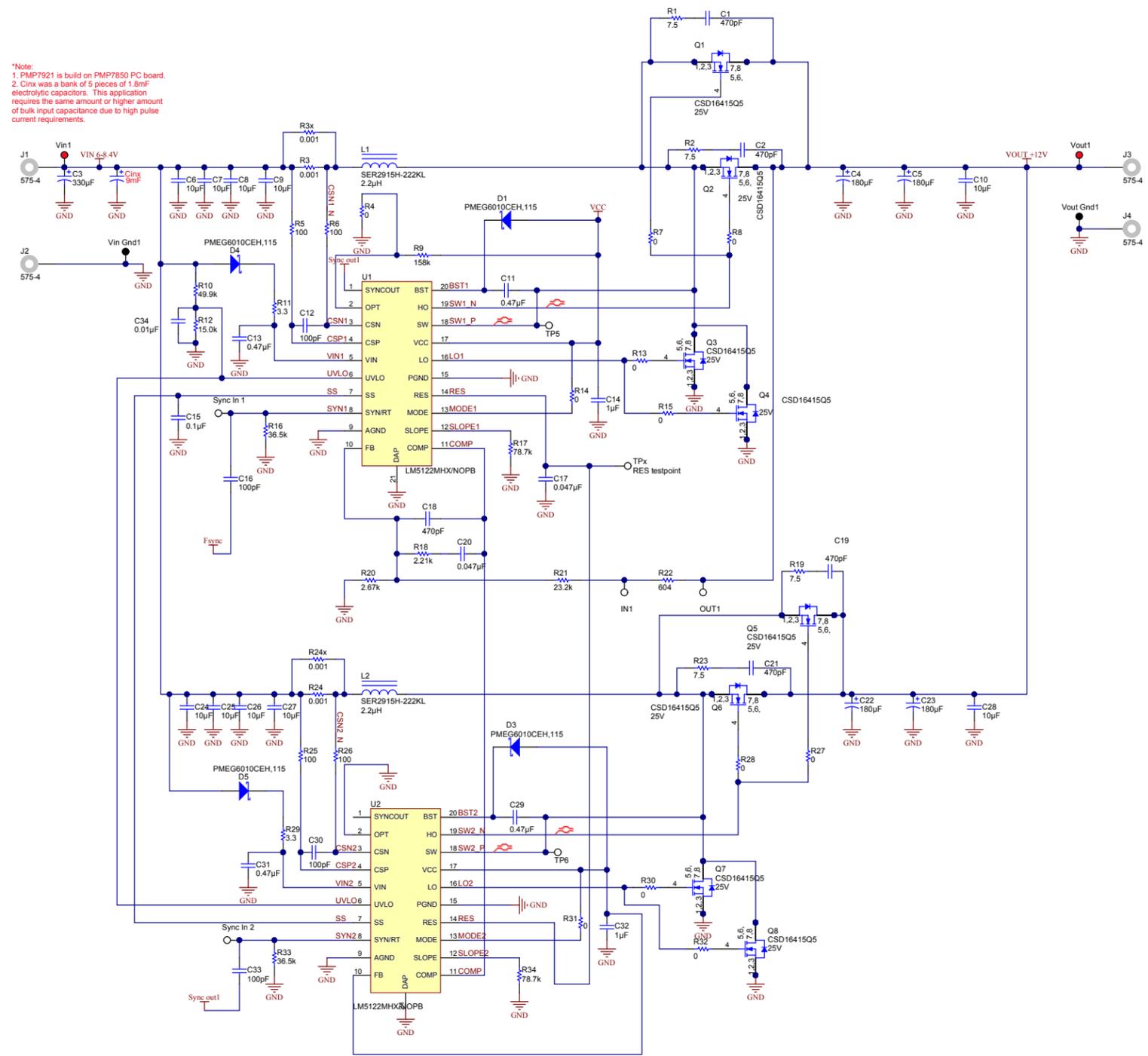


\*Note:  
 1. PMP7921 is built on PMP7850 PC board.  
 2. Cinx was a bank of 5 pieces of 1.8mF electrolytic capacitors. This application requires the same amount or higher amount of bulk input capacitance due to high pulse current requirements.



**DNP**  
FID1

**DNP**  
FID2

**DNP**  
FID3

PCB: PMP7850 RevB  
PMP7850 RevB

PCB  
LOGO  
Texas Instruments

Label Table	
Variant	Label Text
001	

ZZ2  
**Assembly Note**  
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3  
**Assembly Note**  
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4  
**Assembly Note**  
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Orderable: N/A	Designed for: Public Release	Mod. Date: 9/22/2015
TID #: PMP7921	Project Title: LM5122 Dual Phase Boost	
Number: PMP7921	Rev: 1	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 2
Drawn By:	File: PMP7921_Hardware.SchDoc	Size: B
Engineer: Hrag Kasparian	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	



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